

# 1A, 200V-1000V Fast Recovery Surface Mount Rectifiers

#### **FEATURES**

- Glass passivated junction chip
- Ideal for automated placement
- Low power loss, high efficiency
- Fast switching for high efficiency
- Low profile package
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

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- High frequency rectification
- Freewheeling application
- Switching mode converters and inverters, computer and telecommunication.

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- Case: Thin SMA
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Pure tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.029 g (approximately)

KEY PARAMETERS						
PARAMETER	VALUE	UNIT				
I <sub>F</sub>	1	Α				
$V_{RRM}$	200-1000	٧				
I <sub>FSM</sub>	30	Α				
T <sub>J MAX</sub>	150	°C				
Package	Thin SMA					
Configuration	Single Die					







Thin SMA

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)								
PARAMETER		SYMBOL	RS1DAL	RS1GAL	RS1JAL	RS1KAL	RS1MAL	UNIT
Marking code on the dev	ice		RS1DAL	RS1GAL	RS1JAL	RS1KAL	RS1MAL	
Repetitive peak reverse	voltage	$V_{RRM}$	200	400	600	800	1000	V
Reverse voltage, total rm	ns value	V <sub>R(RMS)</sub>	140	280	420	560	700	V
Forward current		I <sub>F</sub>	1					Α
Surge peak forward current, single half sine-	8.3ms at T <sub>A</sub> = 25°C		30					Α
wave superimposed on rated load per diode $1.0 \text{ms}$ at $T_A = 25 ^{\circ}\text{C}$		I <sub>FSM</sub>	100					Α
Junction temperature	TJ	-55 to +150					°C	
Storage temperature	T <sub>STG</sub>	-55 to +150					°C	



THERMAL PERFORMANCE							
PARAMETER	SYMBOL	TYP	UNIT				
Junction-to-lead thermal resistance	$R_{\Theta JL}$	19	°C/W				
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	81	°C/W				
Junction-to-case thermal resistance	R <sub>eJC</sub>	19	°C/W				

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)						
PARAMET	ER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
		I <sub>F</sub> = 0.5A, T <sub>J</sub> = 25°C		0.90	-	V
	RS1DAL	I <sub>F</sub> = 1.0A, T <sub>J</sub> = 25°C	=	0.97	1.30	V
	RS1GAL RS1JAL	I <sub>F</sub> = 0.5A, T <sub>J</sub> = 125°C	-	0.75	-	V
<b>5</b> (1)		I <sub>F</sub> = 1.0A, T <sub>J</sub> = 125°C		0.83	0.94	V
Forward voltage <sup>(1)</sup>		I <sub>F</sub> = 0.5A, T <sub>J</sub> = 25°C	V <sub>F</sub>	0.96	-	V
	RS1KAL	I <sub>F</sub> = 1.0A, T <sub>J</sub> = 25°C		1.04	1.30	V
	RS1MAL	I <sub>F</sub> = 0.5A, T <sub>J</sub> = 125°C		0.80	-	V
		I <sub>F</sub> = 1.0A, T <sub>J</sub> = 125°C		0.90	1.11	V
Davidada a comunita de material V	(2)	T <sub>J</sub> = 25°C		-	1	μΑ
Reverse current @ rated V <sub>R</sub>		T <sub>J</sub> = 125°C	- I <sub>R</sub>	-	33	μA
	RS1DAL RS1GAL		t <sub>rr</sub>	-	150	ns
Reverse recovery time	RS1JAL	I <sub>F</sub> =0.5A,I <sub>R</sub> =1.0A, Irr=0.25A		-	250	ns
	RS1KAL RS1MAL			-	500	ns
Junction capacitance		1 MHz, V <sub>R</sub> =4.0V	CJ	7	-	pF

## Notes:

- (1) Pulse test with PW=0.3 ms
- (2) Pulse test with PW=30 ms

ORDERING INFORMATION						
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING				
RS1xAL M3G	Thin SMA	3,500 / 7" reel				
RS1xAL M2G	Thin SMA	14,000 / 13" reel				

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#### Notes:

(1) "x" defines voltage from 200V(RS1DAL) to 1000V(RS1MAL)



#### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Forward Current Derating Curve** 

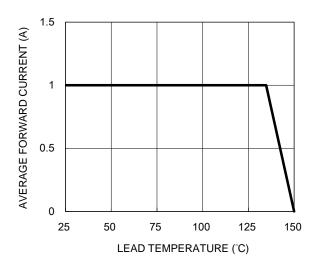


Fig.3 Typical Reverse Characteristics

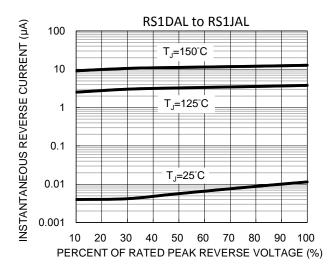


Fig.5 Typical Reverse Characteristics

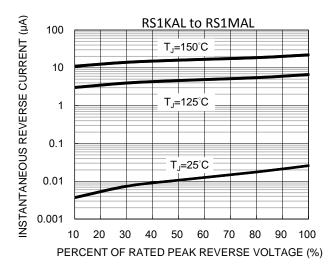


Fig.2 Typical Junction Capacitance

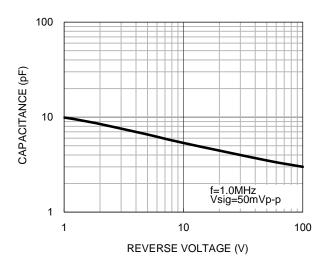


Fig.4 Typical Forward Characteristics

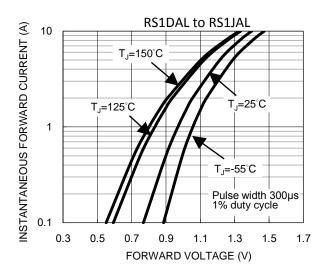
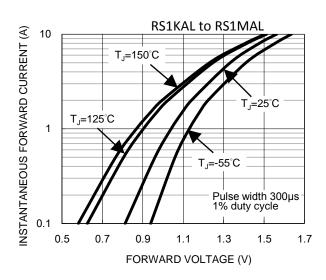


Fig.6 Typical Forward Characteristics





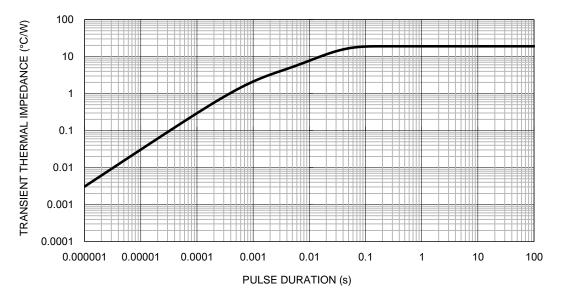
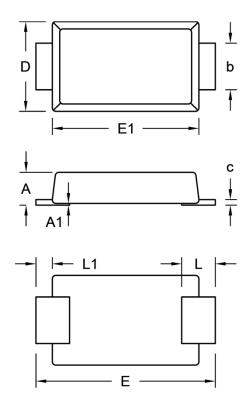


Fig.7 Typical Transient Thermal Impedance



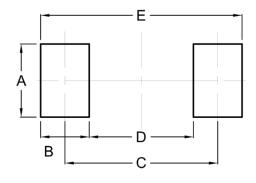
# **PACKAGE OUTLINE DIMENSIONS**

Thin SMA



DIM.	Unit	(mm)	Unit (inch)		
Dilvi.	Min.	Max.	Min.	Max.	
Α	0.90	1.00	0.035	0.039	
A1	0.00	0.10	0.000	0.004	
b	1.25	1.45	0.049	0.057	
С	0.10	0.22	0.004	0.009	
D	2.50	2.70	0.098	0.106	
E	5.05	5.35	0.199	0.211	
E1	4.15	4.35	0.163	0.171	
L	0.75	1.20	0.030	0.047	
L1	0.30	0.60	0.012	0.024	

# **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	2.10	0.083
В	1.40	0.055
С	4.40	0.173
D	3.00	0.118
E	5.80	0.228

# **MARKING DIAGRAM**



P/N = Marking Code YW = Date Code F = Factory Code

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